

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q73159

Hien Boon TAN, et al.

Appln. No.: 10/721,384

Group Art Unit: Not Yet Assigned

Confirmation No.: Not Yet Assigned

Examiner: Not Yet Assigned

Filed: November 25, 2003

For: HIGH PER

HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE AND METHOD OF

MANUFACTURING THE PACKAGE

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §§ 1.97 and 1.98

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56, Applicants hereby notify the U.S. Patent and Trademark Office of the documents which are listed on the attached PTO/SB/08 A & B (modified) form and/or listed herein and which the Examiner may deem material to patentability of the claims of the above-identified application.

Serial No. Applicant's Name Filing Date

10/721,382 Hien Boon TAN et al. November 26, 2003

One copy of each of the listed documents, other than any U.S. patents and patent publications, is submitted herewith.

The present Information Disclosure Statement is being filed: (1) No later than three months from the application's filing date; (2) Before the mailing date of the first Office Action

INFORMATION DISCLOSURE STATEMENT

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on the merits (whichever is later); or (3) Before the mailing date of the first Office Action after

filing a request for continued examination (RCE) under §1.114, and therefore, no Statement

under 37 C.F.R. § 1.97(e) or fee under 37 C.F.R. § 1.17(p) is required.

The submission of the listed documents is not intended as an admission that any such

document constitutes prior art against the claims of the present application. Applicants do not

waive any right to take any action that would be appropriate to antedate or otherwise remove any

listed document as a competent reference against the claims of the present application.

The USPTO is directed and authorized to charge all required fees, except for the Issue

Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any

overpayments to said Deposit Account. A duplicate copy of this paper is attached.

Respectfully submitted,

Registration No. P-55,470

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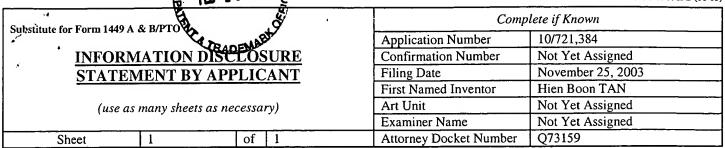
WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Date: February 25, 2004

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U.S. PATENT DOCUMENTS							
Examiner Initials*	Cite No.1	Document Number		Publication Date			
		Number	Kind Code ² (if known)	MM-DD-YYYY	Name of Patentee or Applicant of Cited Document		
		US 5,363,279	A	11-18-1994	CHA		
		US 5,428,248	A	06-27-1995	СНА		
		US 6,433,277	B1	08-13-2002	GLENN		
		US 6,630,371	B2	10-17-2003	HEMBREE		
		US 6,444,498	B1	09-03-2002	HUANG et al.		
		US 6,177,718	B1	01-23-2001	KOZONO		
		US 5,894,108	Α	08-13-1999	MOSTAFAZADEH et al.		
		US 5,519,251	A	05-21-1996	SATO et al.		
	•	US 5,770,888	Α	06-21-1998	SONG et al.		
		US 6,166,430	A	12-26-2000	YAMAGUCHI		
	·	US 5,789,280	A	08-04-1998	YOKOTA		

FOREIGN PATENT DOCUMENTS							
Examiner Initials*	Cite No. ¹	Foreign Patent Document			Publication Date	Name of Patentee or	
		Country Code ³	Number ⁴	Kind Code ⁵ (if known)	MM-DD-YYYY	Applicant of Cited Document	Translation ⁶
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	NON PATENT LITERATURE DOCUMENTS	···		
Cite No.1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where publisher			
	Internet Article: Jim Lipman, "NEW IC Packages really pack in the leads", EDN Access, September 1, 1997			
	Internet Article: Ultra BGA, "Circuitize the Heatsink", Substrate Technologies, Inc Ultra Technology Family			
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	No. ¹	Internet Article: Jim Lipman, "NEW IC Packages really pack in the leads", EDN Access, September 1, 1997 Internet Article: Ultra BGA, "Circuitize the Heatsink", Substrate Technologies, Inc Ultra Technology		

Examiner Signature	 Date Considered	

^{*}EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered: Include copy of this form with next communication to applicant.

¹Applicant's unique citation designation number (optional). ²See Kind Codes of USPTO Patent Documents at www.uspto.gov, MPEP 901.04 or in the comment box of this document. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST. 3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ³Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to indicate here if English language Translation is attached.